

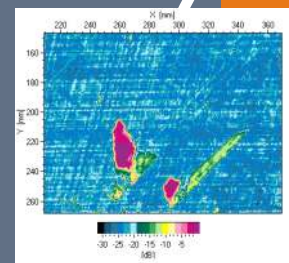
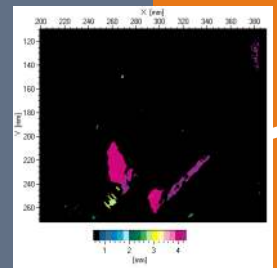
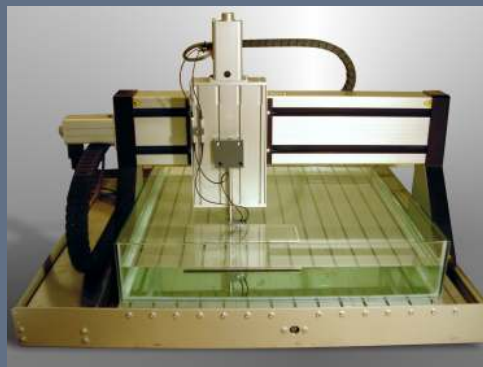
USPC 3040 Ultrasonic Imaging System

Highlights

- High resolution ultrasonic imaging
- Easy handling
- Modular design
- Basic version: A-, C- and D-scans
- Instruction and initial operation on location
- Training by request

Applications

- Quality control
- Testing of metallic, ceramic and composite materials
- Indication of internal defects like debondings, inclusions, and delaminations
- Research and development



The ultrasonic imaging systems **USPC 3010/3040** provide high resolution, multiple applications and easy handling. The system consists of a 19" rack containing the ultrasonic system and the motor controller. Additionally, the scanner with probe holder and basin are included. The modular design enables both easy upgrades and/or modification for new applications even after several years.

Options:

- Hardware-distance amplitude control, scaled in dB/ μ s or dB/mm
- Enlarged frequency range up to 60 MHz
- Digital highpass and lowpass filters
- B- scans (side views)
- 12 or 14 Bit ADC up to 500 Ms/s
- Fast full-wave data recording
- Burst-transmitter for materials with high sound attenuation such as sandwich components or foam
- Mobile scanner (MUSE)
- Scanner with enlarged area (500x 500mm, or even larger)

